



TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	System, Method and Apparatus for Constructing a Semiconductor Wafer-Interposer Using B-Stage Laminates															
Application Number: 09/738193 Date: 2003-07-14 First Named Applicant: Mr. John L. Pierce Confirmation Number: 1129 Attorney Docket Number: 1384-1023																
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
Submitted by:	Elec. Sign.	Sign. Capacity														
Mr. Scott T. Griggs Registered Number: 48,331	/Scott T. Griggs/	Attorney														
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-fee-sheet</td><td>IDS-usfees.xml</td></tr><tr><td></td><td>us-fee-sheet.xml</td></tr><tr><td></td><td>us-fee-sheet.dtd</td></tr><tr><td>us-ids</td><td>IDS-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xml</td></tr></table>			Documents being submitted	Files	us-fee-sheet	IDS-usfees.xml		us-fee-sheet.xml		us-fee-sheet.dtd	us-ids	IDS-usidst.xml		us-ids.dtd		us-ids.xml
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Comments

**FEE TRANSMITTAL**

Electronic Version v08
Stylesheet Version v08.0

Title of Invention	System, Method and Apparatus for Constructing a Semiconductor Wafer-Interposer Using B-Stage Laminates										
Application Number: 09/738193 Date: 2003-07-14 First Named Applicant: Mr. John L. Pierce Attorney Docket Number: 1384-1023 Art Unit: 2827 Examiner: Mr. David E. Graybill											
TOTAL FEE AUTHORIZED \$180 Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION The commissioner is hereby authorized to charge indicated fees and credit any overpayments to: Credit account number: 2005 Expiration Date (YYYYMMDD): 2005-09-30 Authorized name: Lawrence R. Youst Billing address: 75230											